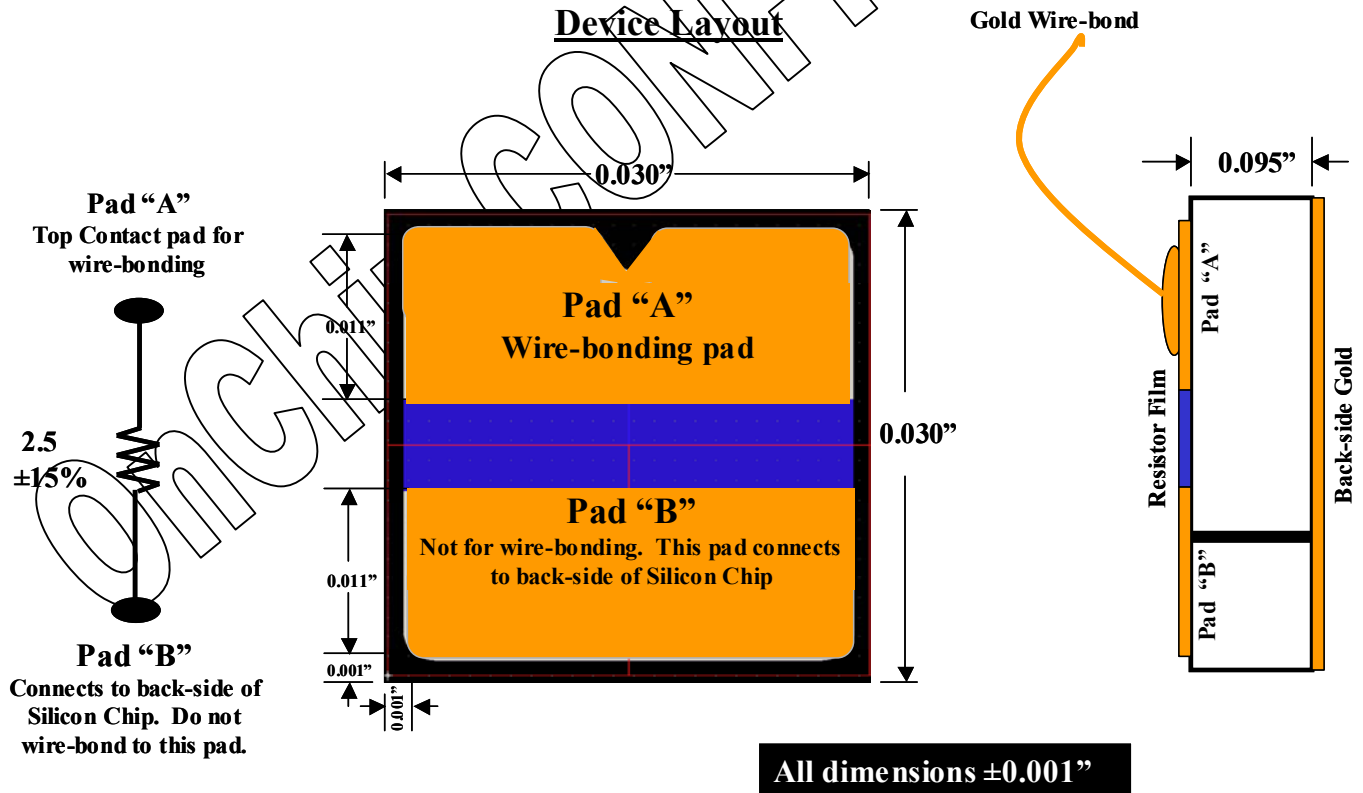


Thin Film Back-Contact Silicon Resistor Chip

OnChip Devices' OCRN101 is a back-contact silicon resistor with chip a size of 30 x 30 mils sq.. Conductive epoxy or eutectic die-attachment to an active substrate area eliminates the need for a second wire bond. This silicon resistor chip is built using the high reliable Tantalum Nitride resistor material. This product offers a very high degree of stability, extremely low Temperature Coefficient of Resistance and exceptionally low noise.

ELECTRICAL	
Operating Temperature Range	-55°C to 125°C
Resistance	2.5 Ohms
Resistance Tolerance at 25°C (%)	± 15%
Maximum Power Rating @ 25°C	250mW
Temperature Coefficient of Resistance	0 to -250ppm/°C
Voltage Rating	100V
Noise, Maximum (MIL-STD-202, Method 308)	-30dB
Maximum Shunt Capacitance	0.5pF

Device Layout



OBJECTIVE DATA SHEET

OnChip

OCRN101

MECHANICAL	
Resistive Film	Tantalum Nitride
Substrate Material	Silicon
Isolation Layer	Silicon dioxide
Bonding Pads	Gold
Back Metal	Gold
Passivation Layer	Tantalum pentoxide
Die size	30 x 30 mils sq. +/- 1 mil
Die thickness	9.5 mils +/- 0.5 mil

Ordering Part Number: OCRN101-BR

Packaging: Parts will be shipped in 2" square trays (Waffle Packs). 400 chips maximum per tray is standard.

This document supercedes all previous specifications.

Please contact the factory for further details on this product.